

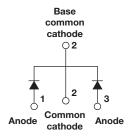
www.vishay.com

Vishay Semiconductors

HEXFRED®, Ultrafast Soft Recovery Diode, 2 x 15 A



D²PAK (TO-263AB)



PRIMARY CHARACTERISTICS								
I _{F(AV)}	2 x 15 A							
V _R	600 V							
V _F at I _F	1.2 V							
t _{rr} (typ.)	19 ns							
T _J max.	150 °C							
Package	D ² PAK (TO-263AB)							
Circuit configuration	Common cathode							

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- · Specified at operating conditions
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

(Pb)

ROHS COMPLIANT HALOGEN

FREE

BENEFITS

- · Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- · Reduced parts count

DESCRIPTION

VS-HFA30TA60CS is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 15 A per leg continuous current, the VS-HFA30TA60CS is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA30TA60CS is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Cathode to anode voltage	V_{R}		600	V					
Maximum continuous forward current per leg	1_	T _C = 100 °C	15						
per device	e I _F	1C = 100 C	30	Α					
Single pulse forward current	I _{FSM}		150	A					
Maximum repetitive forward current	I _{FRM}		60						
Maximum nawar dissination	В	T _C = 25 °C	74	°C					
Maximum power dissipation	P_{D}	T _C = 100 °C	29]					
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	W					





ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA	600	-	-				
Maximum forward voltage		I _F = 15 A		-	1.3	1.7	V		
	V_{FM}	I _F = 30 A	See fig. 1	-	1.5	2.0			
		I _F = 15 A, T _J = 125 °C		-	1.2	1.6			
Maximum reverse		V _R = V _R rated	Coofie 0	-	1.0	10	μА		
leakage current	I _{RM}	$T_J = 125$ °C, $V_R = 0.8 \times V_R$ rated	See fig. 2	-	400	1000			
Junction capacitance	C _T	V _R = 200 V See fig. 3		-	25	50	pF		
Series inductance	L _S	Measured lead to lead 5 mm from p	-	8.0	-	nH			

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS			
	t _{rr}	$I_F = 1.0 \text{ A}, dI_F/dt = 200$	-	19	-				
Reverse recovery time See fig. 5, 10	t _{rr1}	T _J = 25 °C		-	42	60	ns		
360 lig. 5, 10	t _{rr2}	T _J = 125 °C	I _F = 15 A	-	70	90			
Peak recovery current	I _{RRM1}	T _J = 25 °C		-	4.0	6.0	- A - nC		
See fig. 6	I _{RRM2}	T _J = 125 °C		-	6.5	10			
Reverse recovery charge	Q _{rr1}	T _J = 25 °C	dl _F /dt = 200 A/μs V _B = 200 V	-	80	180			
See fig. 7	Q _{rr2}	T _J = 125 °C	V _R = 200 V	-	220	450			
Peak rate of fall of recovery current during t _b See fig. 8	dI _{(rec)M} /dt1	T _J = 25 °C		-	188	-	A/µs		
	dI _{(rec)M} /dt2	T _J = 125 °C		-	160	-			

THERMAL - MECHANICAL SPECIFICATIONS PER LEG									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C			
Junction to case, single leg conducting	В		-	-	1.7				
Junction to case, both legs conducting	R _{thJC}		-	-	0.85	K/W			
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	80				
Weight			-	2.0	-	g			
vveignt			-	0.07	-	oz.			
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)			
Marking device		Case style D ² PAK (TO-263AB)		HFA30TA60CS					

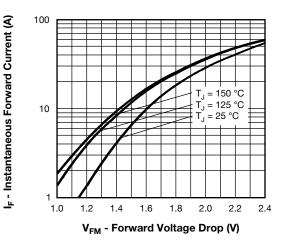


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

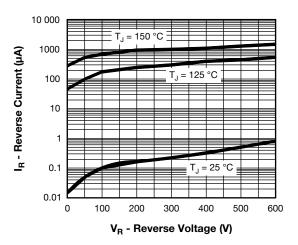


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

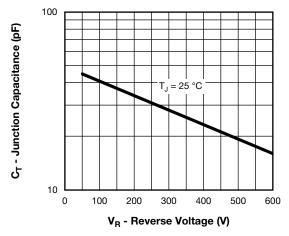


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

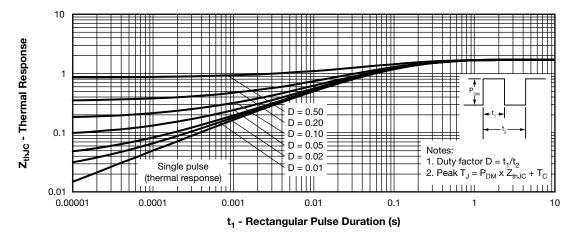


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)



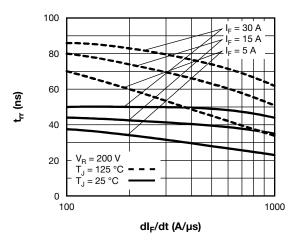


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

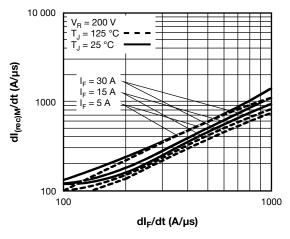


Fig. 8 - Typical dl_{(rec)M}/dt vs. dl_F/dt (Per Leg)

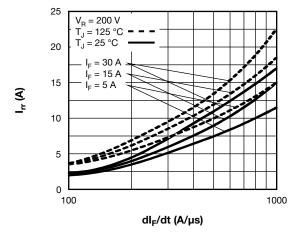


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

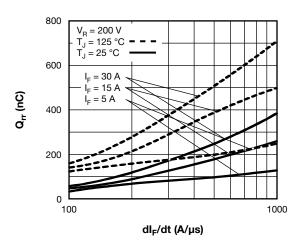
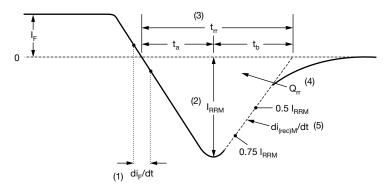


Fig. 7 - Typical Stored Charge vs. dI_F/dt (Per Leg)



- di_F/dt rate of change of current through zero crossing
- (2) $\mathbf{I}_{\mathsf{RRM}}$ peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

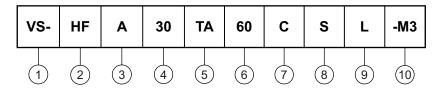
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



- Vishay Semiconductors product
- 2 HEXFRED® family
- **3** Process designator: A = electron irradiated
- 4 Current rating (30 = 30 A)
- 5 Package outline (TA = TO-220, 3 leads)
- Voltage rating (60 = 600 V)
- 7 Circuit configuration (C = common cathode)
- **8** $S = D^2PAK (TO-263AB)$
- 9 • None = tube
 - L = tape and reel (left oriented)
 - R = tape and reel (right oriented)
- 10 Environmental digit
 - -M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free





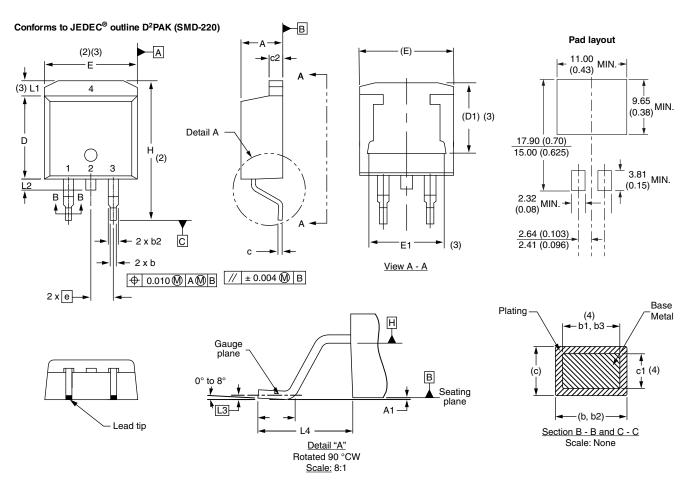
ORDERING INFORMATION (Example)									
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION							
VS-HFA30TA60CS-M3	50	Antistatic plastic tube							
VS-HFA30TA60CSR-M3	800	13" diameter reel							
VS-HFA30TA60CSL-M3	800	13" diameter reel							

LINKS TO RELATED DOCUMENTS						
Dimensions <u>www.vishay.com/doc?96164</u>						
Part marking information	www.vishay.com/doc?95444					
Packaging information	www.vishay.com/doc?96424					



D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190		D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010		E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039		E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4	e 2.54 BSC		0.100	0.100 BSC		
b2	1.14	1.78	0.045	0.070		Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4	L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029		L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4	L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065		L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2	L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

Revision: 13-Jul-17 Document Number: 96164



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